ECE 571 – Advanced Microprocessor-Based Design Lecture 5

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Announcements

- HW#2 was posted
- HW#1 Mostly graded



HW#1 Review

- bzip2 benchmark what does it do?
- 19 billion instructions +/- 400 or so (this is test input maybe?)
- 13 billion cycles +/- 6 million?
- Reversed: similar HW2 will show you why I asked that
- Perf record: 3.5s,

| 66.48% | bzip2 | bzip2 |
|--------|-------|-------|
| 17.45% | bzip2 | bzip2 |
| 6.42% | bzip2 | bzip2 |
| 6.12% | bzip2 | bzip2 |
| 0.70% | bzip2 | bzip2 |

- [.] mainSort
- [.] BZ2_compressBlock
- [.] mainGtU.part.0
- [.] handle_compress.isra.2
- [.] add_pair_to_block



• Valgrind, 1m10.189s == roughly 20 times slower?

11,291,448,187 ???:mainSort [/opt/ece571/401.bzip2/bzip2]
3,381,835,437 ???:BZ2_compressBlock [/opt/ece571/401.bzip2/bzip2]
2,138,813,059 ???:handle_compress.isra.2 [/opt/ece571/401.bzip2/bzip2]
1,958,107,443 ???:mainGtU.part.0 [/opt/ece571/401.bzip2/bzip2]
165,396,105 ???:BZ2_blockSort [/opt/ece571/401.bzip2/bzip2]
140,068,091 ???:add_pair_to_block [/opt/ece571/401.bzip2/bzip2]

Gprof, also 3.5s
 Different results, using function entry instead of exact instruction count for sampling?

| time | seconds | seconds | calls | s/call | s/call | name |
|-------|---------|---------|---------|--------|--------|----------------|
| 71.77 | 2.16 | 2.16 | 53 | 0.04 | 0.04 | mainSort |
| 18.94 | 2.73 | 0.57 | 53 | 0.01 | 0.05 | BZ2_compressB |
| 6.98 | 2.94 | 0.21 | 12223 | 0.00 | 0.00 | default_bzall |
| 1.00 | 2.97 | 0.03 | 1272 | 0.00 | 0.00 | BZ2_hbMakeCode |
| 0.66 | 2.99 | 0.02 | 1856468 | 0.00 | 0.00 | add_pair_to_b |



• Skid instructions – mov is more likely than sub?

perf annotate:

| 1.14 | 5f0: | mov | (%r10),%edx |
|------|------|--------|--------------------|
| 0.56 | | lea | (%rdx,%r13,1),%eax |
| 0.80 | | movzbl | (%r15,%rax,1),%eax |
| 3.29 | | sub | %r9d,%eax |

instructions:pp

perf annotate:

| 0.78 | 5f0: | mov | (%r10),%edx |
|------|------|--------|--------------------|
| 0.88 | | lea | (%rdx,%r13,1),%eax |
| 3.14 | | movzbl | (%r15,%rax,1),%eax |
| 0.99 | | sub | %r9d,%eax |
| 0.52 | | cmp | \$0x0,%eax |
| 0.58 | | jne 6 | 589 |
| 0.90 | | movslq | %ebx,%rax |



Power and Energy



Definitions and Units

People often say Power when they mean Energy

- Energy Joules, kWH (3.6MJ), Therm (105.5MJ), 1 Ton TNT (4.2GJ), eV (1.6×10^{-19} J), BTU (1055 J), horsepower-hour (2.68 MJ), calorie (4.184 J)
- Power Energy/Time Watts (1 J/s), Horsepower (746W), Ton of Refrigeration (12,000 Btu/h)
- \bullet Volt-Amps (for A/C) same units as Watts, but not same thing
- Charge mAh (batteries) need V to convert to Energy



Power and Energy in a Computer System

Power Consumption Breakdown on a Modern Laptop, A. Mahersi and V. Vardhan, PACS'04.

- Old, but hard to find thorough breakdowns like this
- Thinkpad Laptop, 1.3GHz Pentium M, 256M, 14" display
- Oscilloscope with voltage probe and clamp-on current probe.
- Measured V and Current. P=IIR. V=IR P=IV, subtractive for things without wires



- Total System Power 14-30W
 - \circ Hard Drive 0.5-2W (Flash/SSD less)
 - \circ LCD 1W (slightly more black than white)
 - Backlight Inverter (this is before LED) 1-4W depending on brightness
 - \circ CPU 2-15W (with scaling)
 - GPU 1-5W
 - Memory 0.45 1.5W
 - \circ Power Supply Loss 0.65W
 - Wireless 0.1 3W (wifi on cellphones)
 - CDROM 3-5W

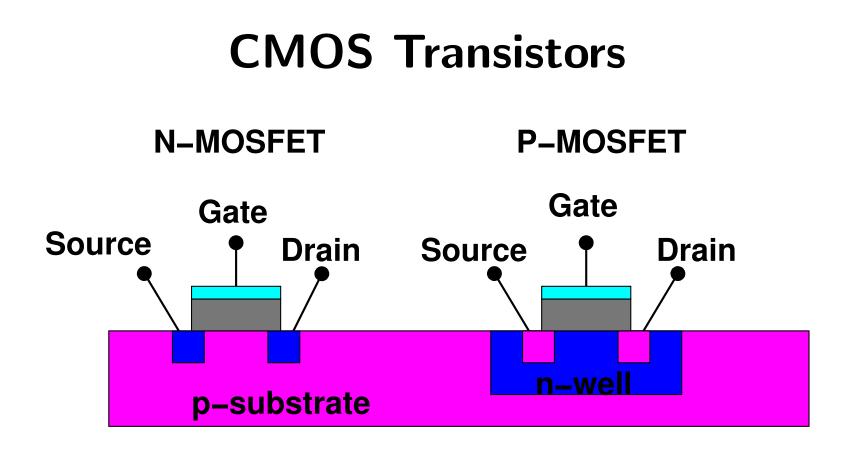


 Not in paper but USB 2.0 – 5V, can draw 5 units of 100mA each, 2.5W)



CPU Power and Energy







CMOS Dynamic Power

- $P = C\Delta V V_{dd} \alpha f$ Charging and discharging capacitors big factor $(C\Delta V V_{dd})$ from V_{dd} to ground α is activity factor, transitions per clock cycle F is frequency
- α often approximated as $\frac{1}{2}$, ΔVV_{dd} as V_{dd}^2 leading to $P\approx \frac{1}{2}CV_{dd}^2f$
- Some pass-through loss (V momentarily shorted)



CMOS Dynamic Power Reduction

How can you reduce Dynamic Power?

- Reduce C scaling
- Reduce V_{dd} eventually hit transistor limit
- Reduce α (design level)
- Reduce f makes processor slower



CMOS Static Power

- Leakage Current bigger issue as scaling smaller.
 Forecast at one point to be 20-50% of all chip power before mitigations were taken.
- Various kinds of leakage (Substrate, Gate, etc)
- Linear with Voltage: $P_{static} = I_{leakage}V_{dd}$



Leakage Mitigation

- SOI Silicon on Insulator (AMD, IBM but not Intel)
- High-k dielectric instead of SO2 use some other material for gate oxide (Hafnium)
- Transistor sizing make only the critical transistors fast; non-critical ones can be made slower and less leakage prone
- Body-biasing
- Sleep transistors



Total Energy

- $E_{tot} = [P_{dyanmic} + P_{static}]t$
- $E_{tot} = [(C_{tot}V_{dd}^2\alpha f) + (N_{tot}I_{leakage}V_{dd})]t$



Delay

- $T_d = \frac{C_L V_{dd}}{\mu C_{ox}(\frac{W}{L})(V_{dd} V_t)}$
- Simplifies to $f_{MAX} \sim \frac{(V_{dd} V_t)^2}{V_{dd}}$
- \bullet If you lower f, you can lower V_{dd}



Thermal Issues

- Temperature and Heat Dissipation are closely related to Power
- If thermal issues, need heatsinks, fans, cooling



Metrics to Optimize

- Power
- Energy
- MIPS/W, FLOPS/W (don't handle quadratic V well)
- Energy * Delay
- $Energy * Delay^2$



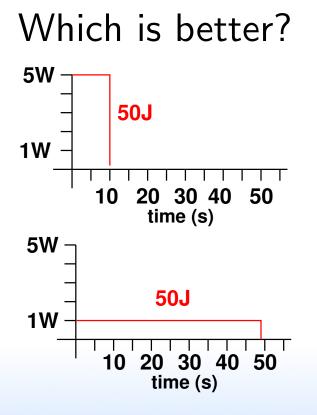
Power Optimization

• Does not take into account time. Lowering power does no good if it increases runtime.



Energy Optimization

• Lowering energy can affect time too, as parts can run slower at lower voltages





Energy Delay – Watt/t*t

- Horowitz, Indermaur, Gonzalez (Low Power Electronics, 1994)
- Need to account for delay, so that lowering Energy does not made delay (time) worse
- Voltage Scaling in general scaling low makes transistors slower
- Transistor Sizing reduces Capacitance, also makes transistors slower



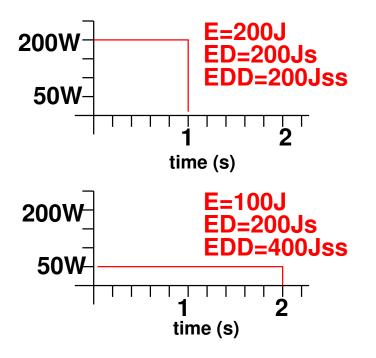
- Technology Scaling reduces V and power.
- Transition Reduction better logic design, have fewer transitions

Get rid of clocks? Asynchronous? Clock-gating?



ED Optimization

Which is better?





Energy Delay Squared– E*t*t

- Martin, Nyström, Pénzes Power Aware Computing, 2002
- Independent of Voltage in CMOS
- Et can be misleading Ea=2Eb, ta=tB/2 Reduce voltage by half, Ea=Ea/4, ta=2ta, Ea=Eb/2, ta=tb
- Can have arbitrary large number of delay terms in Energy product, squared seems to be good enough



Energy Delay / Energy Delay Squared

Lower is better.

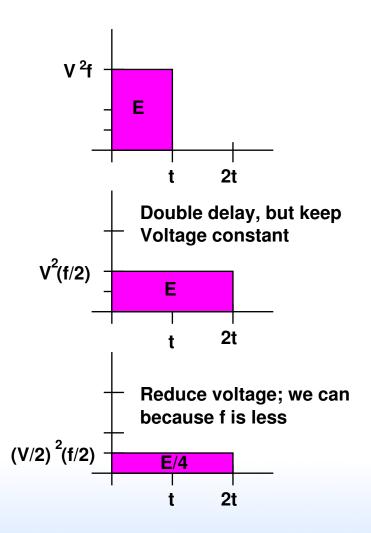
| Energy | Delay | ED | ED^2 |
|--------|-------|------|----------|
| 5 J | 2s | 10Js | $20Js^2$ |
| 5J | 3s | 15Js | $45Js^2$ |

Same ED, Different ED^2

| Energy | Delay | ED | ED^2 |
|--------|-------|------|------------|
| 5J | 2s | 10Js | $20Js^2$ |
| 2J | 5s | 10Js | $50 J s^2$ |

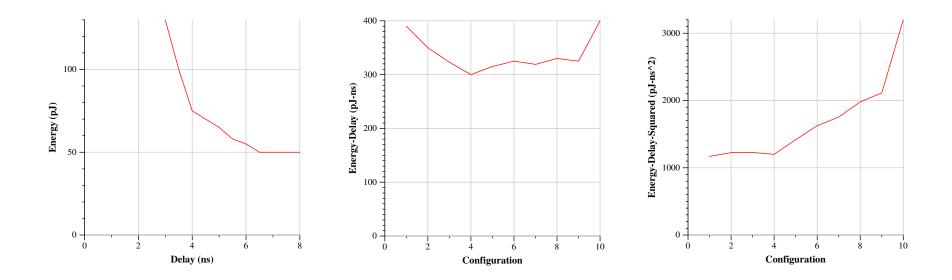


Energy Example





Energy-Delay Product Redux



Roughly based on data from "Energy-Delay Tradeoffs in CMOS Multipliers" by Brown et al.



Raw Data

| Delay | Energy | ED | ED^2 |
|-------|--------|-----|--------|
| 3 | 130 | 390 | 1170 |
| 3.5 | 100 | 350 | 1225 |
| 3.8 | 85 | 323 | 1227 |
| 4 | 75 | 300 | 1200 |
| 4.5 | 70 | 315 | 1418 |
| 5 | 65 | 325 | 1625 |
| 5.5 | 58 | 319 | 1755 |
| 6 | 55 | 330 | 1980 |
| 6.5 | 50 | 390 | 2535 |
| 8 | 50 | 400 | 3200 |



Other Metrics

- $Energy Delay^n$ choose appropriate factor
- $Energy Delay Area^2$ takes into account cost (die area) [McPAT]
- Power-Delay units of Energy used to measure switching
- Energy Delay Diagram [SWEEP]

